

L Number	Hits	Search Text	DB	Time stamp
-	22	((immobile) with (chelat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 12:11
-	53	((immobile) same (chelat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 12:16
-	31	((((immobile) same (chelat\$4))) not (((immobile) with (chelat\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 12:19
-	911	((immobile) and (chelat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:32
-	2	((((immobile) and (chelat\$4))) and ((immobile adj particle\$1) and (chelat\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 12:18
-	193	((((immobile) and (chelat\$4))) and ((immobile) and (chelating adj agent)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 12:18
-	172	((((immobile) and (chelat\$4))) and ((immobile) and (chelating adj agent))) not (((immobile) same (chelat\$4))) or (((immobile) with (chelat\$4))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 12:30
-	686	((((immobile) and (chelat\$4))) not ((((immobile) and (chelat\$4))) and ((immobile) and (chelating adj agent))) or (((immobile) same (chelat\$4))) or (((immobile) with (chelat\$4))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 12:47
-	45085	ibm.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 12:48
-	265	international-business-machines.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 15:29
-	48814	international adj business adj machines.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 12:51
-	93874	ibm.as. or international-business-machines.as. or (international adj business adj machines.as.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 12:51
-	80	(ibm.as. or international-business-machines.as. or (international adj business adj machines.as.)) and immobile	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 14:59
-	171	(ibm.as. or international-business-machines.as. or (international adj business adj machines.as.)) and chelat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:32

-	4	((ibm.as. or international-business-machines.as. or (international adj business adj machines.as.)) and immobile) and ((ibm.as. or international-business-machines.as. or (international adj business adj machines.as.)) and chelat\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 12:52
-	171	((ibm.as. or international-business-machines.as. or (international adj business adj machines.as.)) and chelat\$4) not (((174/260) or (174/256) or (174/52.2) or (264/272.11) or (438/126) or (438/127) or (257/778) or (257/779) or (257/772) or (257/789) or (257/780) or (257/787) or (257/788) or (257/795) or (257/632)).CCLS.) and ((immobile) and (chelats4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:12
-	18685	immobile	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 17:29
-	104966	chelats4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:32
-	1906629	(chip) or (wafer) or (ic) or (integrated adj circuit) or (semiconductor adj device) or (electronic adj component) or (electroinc adj device) or (printed adj circuit) or (printed adj wiring) or (circuit adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:37
-	105	immobile and chelat\$4 and ((chip) or (wafer) or (ic) or (integrated adj circuit) or (semiconductor adj device) or (electronic adj component) or (electroinc adj device) or (printed adj circuit) or (printed adj wiring) or (circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 13:48
-	1401	immobile and ((chip) or (wafer) or (ic) or (integrated adj circuit) or (semiconductor adj device) or (electronic adj component) or (electroinc adj device) or (printed adj circuit) or (printed adj wiring) or (circuit adj board))	USPAT	2004/09/19 14:04
-	6300	chelats4 and ((chip) or (wafer) or (ic) or (integrated adj circuit) or (semiconductor adj device) or (electronic adj component) or (electroinc adj device) or (printed adj circuit) or (printed adj wiring) or (circuit adj board))	USPAT	2004/09/27 11:59
-	53	(immobile and ((chip) or (wafer) or (ic) or (integrated adj circuit) or (semiconductor adj device) or (electronic adj component) or (electroinc adj device) or (printed adj circuit) or (printed adj wiring) or (circuit adj board))) and (chelats4 and ((chip) or (wafer) or (ic) or (integrated adj circuit) or (semiconductor adj device) or (electronic adj component) or (electroinc adj device) or (printed adj circuit) or (printed adj wiring) or (circuit adj board)))	USPAT	2004/09/19 14:16
-	1137	chelats4 and (174/\$.ccls. or 29/\$.ccls. or 257/\$.ccls. or 361/\$.ccls.)	USPAT	2004/09/19 14:49
-	2	(chelats4 and (174/\$.ccls. or 29/\$.ccls. or 257/\$.ccls. or 361/\$.ccls.)) and immobile	USPAT	2004/09/19 14:58

-	14	(composition) with (immobile) with (chelate\$ or complex\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 17:44
-	747	(chelate\$4 and ((chip) or (wafer) or (ic) or (integrated adj circuit) or (semiconductor adj device) or (electronic adj component) or (electronic adj device) or (printed adj circuit) or (printed adj wiring) or (circuit adj board))) and (174/\$.ccls. or 29/\$.ccls. or 257/\$.ccls. or 361/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 15:31
-	74	((chelate\$4 and ((chip) or (wafer) or (ic) or (integrated adj circuit) or (semiconductor adj device) or (electronic adj component) or (electronic adj device) or (printed adj circuit) or (printed adj wiring) or (circuit adj board))) and (174/\$.ccls. or 29/\$.ccls. or 257/\$.ccls. or 361/\$.ccls.)) and (high adj molecular adj weight)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 16:04
-	28	immobile adj particle\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 17:29
-	42	(composition) same (immobile) same (chelate\$ or complex\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 17:45
-	28	((composition) same (immobile) same (chelate\$ or complex\$4)) not ((composition) with (immobile) with (chelate\$ or complex\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/19 17:48
-	26564	chelating adj agent	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 10:48
-	11884	(chelating adj agent) or (immobile adj particle\$1)	USPAT	2004/09/24 10:51
-	0	(chelating adj agent) and (immobile adj particle\$1)	USPAT	2004/09/24 10:51
-	28	immobile adj particle\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 15:23
-	746	(composition) with (metal adj ion\$1) with (chelate\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 17:37
-	2	(composition) with (metal adj ion\$1) with (chelate\$4) with (Immobile adj particle\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 17:39
-	3	(composition) with (metal adj ion\$1) with (chelate\$4) with (Immobile)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/24 17:44
-	0	("4and(chelate\$1)and(particle\$1)").PN.	USPAT	2004/09/24 17:46
-	1	((("4707453").PN.) and (chelate\$1) and (particle\$1)	USPAT	2004/09/24 17:50
-	62	((composition) with (metal adj ion\$1) with (chelate\$4)) and (package)	USPAT	2004/09/24 17:51

-	1	((("4707453").PN.) and (chelate\$1) and (particle\$1)) and (package)	USPAT	2004/09/24 18:04
-	1	(particle\$1 adj chelat\$4) and package	USPAT	2004/09/24 18:05
-	3	(particle\$1 adj chelat\$4) and package	USPAT	2004/09/24 18:17
-	5	(particle\$1 adj chelat\$4) and package	USPAT; US-PGPUB	2004/09/24 18:07
-	6	(particle\$1 adj chelat\$4) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/24 18:14
-	0	((("6711423").PN.) and (particle\$1 adj chelat\$4)	USPAT	2004/09/24 18:17
-	0	((("6711423").PN.) and (immobile)	USPAT	2004/09/24 18:17
-	1	((("6711423").PN.) and (chelate\$4)	USPAT	2004/09/24 18:20
-	4540	(chelate\$4) with (epta or ethylenediamine or ethylenediamine or oxylate)	USPAT; US-PGPUB	2004/09/25 16:42
-	587	((chelate\$4) with (epta or ethylenediamine or ethylenediamine or oxylate)) and (electronic adj device or integrated adj circuit or package or printed adj circuit adj board or printed adj wiring adj board or semiconductor adj device or semiconductor adj package)	USPAT; US-PGPUB	2004/09/25 16:46
-	156	((chelate\$4) with (epta or ethylenediamine or ethylenediamine or oxylate)) and (immobile)	USPAT; US-PGPUB	2004/09/25 16:46
-	10	((chelate\$4) with (epta or ethylenediamine or ethylenediamine or oxylate)) and (electronic adj device or integrated adj circuit or package or printed adj circuit adj board or printed adj wiring adj board or semiconductor adj device or semiconductor adj package)) and ((chelate\$4) with (epta or ethylenediamine or ethylenediamine or oxylate)) and (immobile)	USPAT; US-PGPUB	2004/09/25 16:54
-	945	((chelate\$4) with (epta or ethylenediamine or ethylenediamine or oxylate)) and (high adj molecular adj weight)	USPAT; US-PGPUB	2004/09/25 16:55
-	106	((chelate\$4) with (epta or ethylenediamine or ethylenediamine or oxylate)) and (electronic adj device or integrated adj circuit or package or printed adj circuit adj board or printed adj wiring adj board or semiconductor adj device or semiconductor adj package)) and ((chelate\$4) with (epta or ethylenediamine or ethylenediamine or oxylate)) and (high adj molecular adj weight))	USPAT; US-PGPUB	2004/09/26 13:16
-	1239	kline.in.	USPAT	2004/09/25 17:30
-	24	kline.in. and (chelate\$4)	USPAT	2004/09/25 17:48
-	136	(integrated adj circuit) with (scratch)	USPAT; US-PGPUB	2004/09/25 18:38
-	286	(integrated adj circuit) with (scratch\$4)	USPAT; US-PGPUB	2004/09/25 18:38
-	136	((integrated adj circuit) with (scratch)) and ((integrated adj circuit) with (scratch\$4))	USPAT; US-PGPUB	2004/09/25 18:39
-	286	((integrated adj circuit) with (scratch)) or ((integrated adj circuit) with (scratch\$4))	USPAT; US-PGPUB	2004/09/25 18:39
-	10	((integrated adj circuit) with (scratch)) or ((integrated adj circuit) with (scratch\$4)) and chelat\$4	USPAT; US-PGPUB	2004/09/25 18:40
-	0	("(wateradjpollutionadjmonitoring)with(chelat\$4).PN.	USPAT	2004/09/27 11:55
-	1	(water adj pollution adj monitoring) with (chelate\$4)	USPAT	2004/09/27 11:56
-	1119	(analy\$6) with (chelate\$4)	USPAT	2004/09/27 11:57
-	614	((analy\$6) with (chelate\$4)) and (metal adj ion\$4)	USPAT	2004/09/27 11:57

-	624	((analy\$6) with (chelate\$4)) and (metal\$4 adj ion\$4)	USPAT	2004/09/27 11:58
-	327	((analy\$6) with (chelate\$4)) and (metal\$4 adj ion\$4)) and (chelating adj agent)	USPAT	2004/09/27 11:59
-	46	((analy\$6) with (chelate\$4)) and (metal\$4 adj ion\$4)) and (chelating adj agent)) and ((chip) or (wafer) or (ic) or (integrated adj circuit) or (semiconductor adj device) or (electronic adj component) or (electroinc adj device) or (printed adj circuit) or (printed adj wiring) or (circuit adj board))	USPAT	2004/09/27 12:22
-	428	604/\$.ccls. and (chelate\$4)	USPAT	2004/09/27 13:38
-	9	(604/\$.ccls. and (chelate\$4)) and (integrated adj circuit or semiconductor adj chip or integrated adj circuit)	USPAT	2004/09/27 13:44
-	448	427/\$.ccls. and (chelating adj agent)	USPAT	2004/09/27 14:03
-	2838	427/\$.ccls. and (integrated adj circuit)	USPAT	2004/09/27 14:04
-	7174	427/\$.ccls. and (chip or wafer)	USPAT	2004/09/27 14:04
-	43	(427/\$.ccls. and (chelating adj agent)) and (427/\$.ccls. and (chip or wafer))	USPAT	2004/09/27 14:57
-	407	((174/260) or (361/760)).CCLS.) and (encapsul\$6)	USPAT	2004/09/27 20:42
-	297	((174/260) or (361/760)).CCLS.) and (encapsul\$6)) and package	USPAT	2004/09/27 20:22
-	109	((174/260) or (361/760)).CCLS.) and (underfill)	USPAT	2004/09/27 20:42
-	43	((174/260) or (361/760)).CCLS.) and (encapsul\$6)) and package) and ((174/260) or (361/760)).CCLS.) and (underfill))	USPAT	2004/09/27 20:56